

Mar. 10th, 2014

RE: LFPCN41207

To: Our Valued Customers

From: Littelfuse Product Management Team

Subject: LFPCN41207--Approve Wuxi/ Cirtek in Addtion to Existing Fab and Assermbly Site to Provide Capacity and Competitive Lead Time.

Littelfuse would like to notify you that Littelfuse Wuxi wafer Fab will be fully approved as an alternative FVSP Series SIDACTOR chip manufacturing site and Cirtek will be approved as an alternative assembly site. Please refer to table below for affected parts.

There will be no changes to fit, form, shape and function of the finished product in accordance with established performance and reliability qualification criteria.

Please see the attached documentation for change detail and affected part numbers.

Form, fit, function changes: None Part number changes: None Effective date: June 10th, 2014 Replacement products: N/A

Last time buy: N/A

This notification is for your information and acknowledgement. If you have any other questions or concerns, please contact Meng Wang, Assistant Product Manager.

We value your business and look forward to assisting you

Best Regards, Meng Wang Assistant Product Marketing Manager,

Tel: +86 510 85277701, extension 7955

Mwang3@littelfuse.com

Affected Parts Are as Below.

Part Number
P0641DF-1E
P0721DF-1E
P0901DF-1E
P0991DF-1E
P1001DF-1E
P1101DF-1E
P1301DF-1E
P1701DF-1E
P816P1701DF-1E



800 E. Northwest Highway Des Plaines, IL 60016

Product/Process Change Notice (PCN)

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PCN#: LFPCN41207 Date: Mar 10 th 20	14 Contact Information					
Product Identification:	Name: Meng Wang					
Littelfuse FVSP Series SIDACTOR	Title: Assistant Product Manager					
Implementation Date for Change:	Phone #: +86 510 87277955					
June 01 st 2014	Fax#: +86 510 85277700					
	E-mail: mwang3@littelfuse.com					
Category of Change: Des	cription of Change:					
☐ Assembly Process Thro	ough this PCN, Littelfuse would seek approval from customer to qualify					
☐ Data Sheet LItte	elfuse Wuxi as alternative FVSP seris SIDACTOR chip manufacturing					
☐ Technology	and approval for Cirtek as an addtinal assembly site					
☐ Discontinuance/Obsolescence	and approval for entert as an additional assessment sites					
☐ Equipment						
☐ Raw Material						
☐ Testing						
☐ Fabrication Process						
☐ Other:						
Important Dates:						
$oxed{\boxtimes}$ Qualification Samples Available: Mar 10 th	2014					
☐ Final Qualification Data Available: Mar 10	th 2014					
☐ Date of Final Product Shipment: N/A						
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Method of Distinguishing Changed Product	t .					
☐ Product Mark,						
□ Date Code, 4FCxx						
Other,						
Demonstrated or Anticipated Impact on Form, Fit, Function or Reliability:						
N/A						
LF Qualification Plan/Results:						
availabe on Feb 7 th 2014						
Customer Acknowledgement of Receipt: Life	telfuse requests you acknowledge receipt of this PCN. In your acknowledgement, you can					
grant approval or request additional information. Littelfuse will assume the change is acceptable if no acknowledgement is received within 30 days						

of this notice. Lack of any additional response within 90 days of PCN issuance further constitutes acceptance of the change.





FVSP Product Validation & Reliability Summary

PRODUCT FAMILY: P0641DF-1E, P0721DF-1E, P0901DF-1E, P0991DF-1E, P1001DF-1E, P1101DF-1E, P1301DF-1E. TABLE-A

Environmental Tests Validating Structural and Package Intergrity for Conditions Most Likely to be Encountered in Actual Field Applications

Test Standard Listed are per the Mil-Std-750 Unless Otherwise Stated

Test ²	Standard	Test Condition ¹	Pass/Fail Verification Method	Pass Criteria	Test Result; Defects/Sample Size	Data Reference
Pre-conditioning Test	JESD22-A-113 Level 1	24hrs 125°C bake/ 168hrs 85%rh, 85°C sock/3 times	Interim & Post electrical test	Meets Catalog specification	0/120	ETR52066 ETR52067 ETR50102 ETR53360 ETR53359 ETR53363
Temperature Cycle	M-1051, Cond. F	-65°C to +150°C, 15minutes dwell, 100 cycles	Interim & Post electrical test	Meets Catalog specification	0/40	ETR52066 ETR52067 ETR50102 ETR53360 ETR53359 ETR53363
Autoclave	JESD22-A-102	T _A =121°C, RH=100%, 15psig, 96hrs	Interim & Post electrical test	Meets Catalog specification	0/40	ETR52066 ETR52067 ETR50102 ETR53360 ETR53359 ETR53363
Temperature& Humidity with DC Bias (H3TRB)	JESD22-A101	T _A =85°C, RH=85%, 52Vdc, 1008hrs	Interim & Post electrical test	Meets Catalog specification	0/40	ETR52066 ETR52067 ETR50102 ETR53360 ETR53359 ETR53363
Resistance to Solder Heat	MIL-STD-750	260°C, 10s	Interim & Post electrical test	Meets Catalog specification	0/10	ETR52066 ETR52067 ETR50102 ETR53360 ETR53359



FVSP Product Validation & Reliability Summary

						ETR53363
High Temp Storage Life	JESD22-A-101	150°C for 1000hrs	Interim & Post electrical test	Meets Catalog specification	0/40	ETR52066 ETR52067 ETR50102 ETR53360 ETR53359 ETR53363
Moisture Sensitivity Level	JEDEC-J-STD-020 Level 1	85°C, 85%,168hrs, 3 reflow	Interim & Post electrical test	Meets Catalog specification	0/10	ETR52066 ETR52067 ETR50102 ETR53360 ETR53359 ETR53363
Thermal shock	JESD22-A-106	0°C to 100°C,5min Dwell,10s,transfer, 10 cycles	Interim & Post electrical test	Meets Catalog specification	0/40	ETR52066 ETR52067 ETR50102 ETR53360 ETR53359 ETR53363
Solderability	JESD22-B102	Dip &Look, Category-2(Steam Aging)	Visual examination	Meets Catalog specification	0/10	ETR52066 ETR52067 ETR50102 ETR53360 ETR53359 ETR53363

TABLE-B
Reliability Test: Device Performance at Catalog Stated Conditions
All Test Standards Listed Are Per the Mil-Std-750 Unless Otherwise Stated

Test ³	Standard	Test Condition ¹	Pass/Fail Verification Method	Pass Criteria	Test Result; Defects/Sample Size	Data Reference ²
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FVSP Product Validation & Reliability Summary

High Temperature DC Blocking	JESD22-A-101	Rated 80%Vdrm @ TA=150℃ for 1008hrs	Interim & Post electrical test	Meets Catalog specification	0/77	ETR52066 ETR52067 ETR50102 ETR53360 ETR53359 ETR53363
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TABLE-CEstimate of Failure Rate, MTBF, FITS for a Given Operation Temperature (See note 4)

Temp C.	FR	MTBF (K)	FITS
30	0.000199	500463	2
60	0.00314	31754	31.49
85	0.022	4540	220.25
125	0.2799	335.87	2977.37
150	1.18	84.71	11805.44

³.The **M**ean-**T**ime-**B**etween-**F**ailure (MTBF) in hours and the percent failure rate per 1000 hours (%FR/khr) are computed at a 60% confidence level using the chi square method and the Arrhenius derating model for various junction operating temperatures. For the calculations, a value of 1 eV was used for the activation energy.